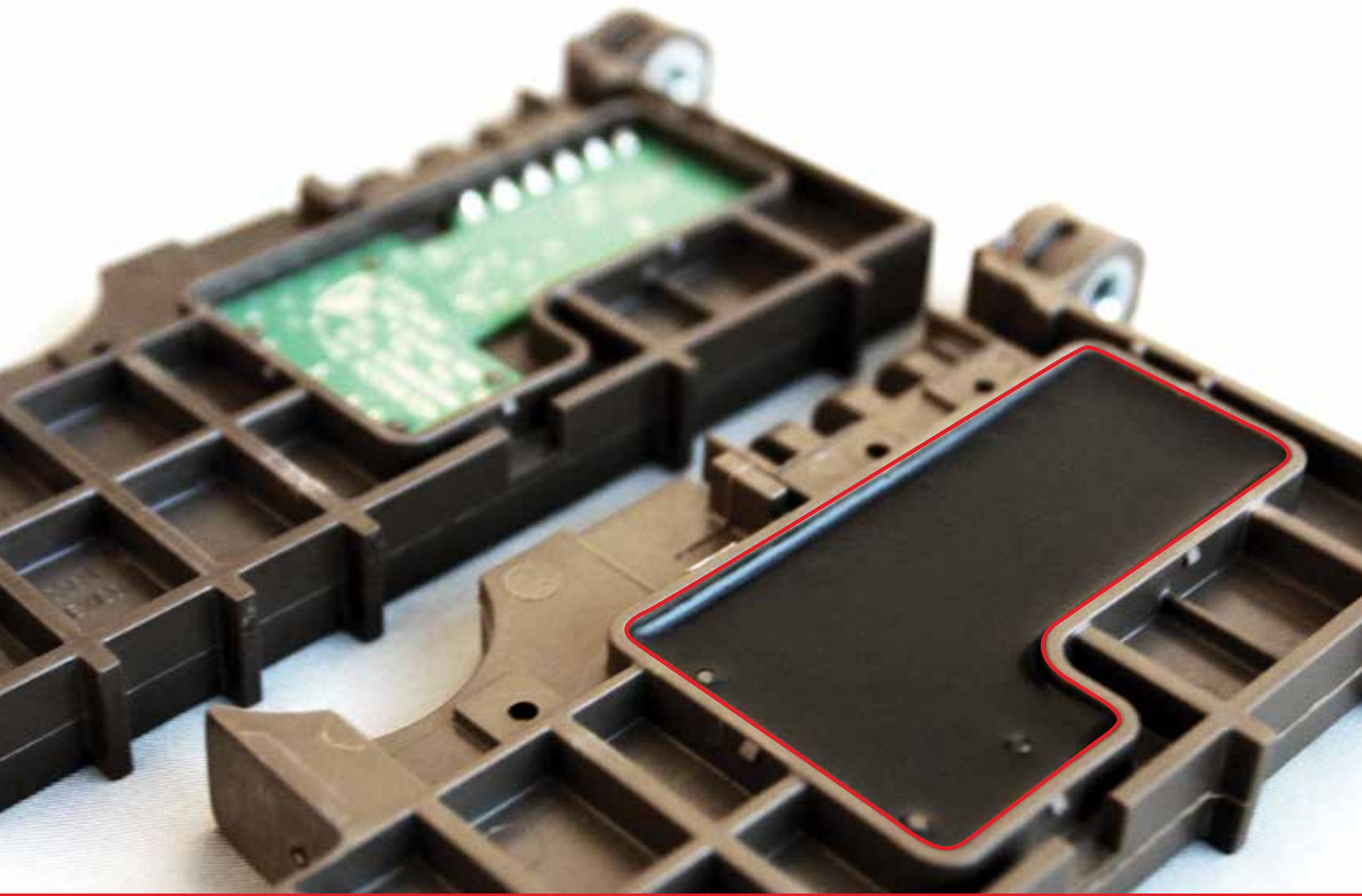


Printed Circuit Board Protection





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For today's electronics products, reliability is critical. Consumers expect unfailing function, uninterrupted long-term use and cost effectiveness. Manufacturing of complex electronic devices requires the highest quality materials to ensure robust performance and superb protection from harsh conditions and environmental influences.

Henkel's broad portfolio of printed circuit board protection materials safeguards electronic components and printed circuit boards (PCBs) from damaging environmental factors, such as extreme temperatures,

fluids, corrosive elements, shock and vibration. Our advanced potting materials, sealants, low pressure molding systems and conformal coatings ensure that even the most complex circuitry is protected. With a wide range of materials for applications that span multiple markets, including automotive, industrial, medical and consumer electronics, Henkel's PCB protection materials deliver comprehensive solutions for a variety of products.



Printed Circuit Board Protection Market Solutions

Automotive Electronics

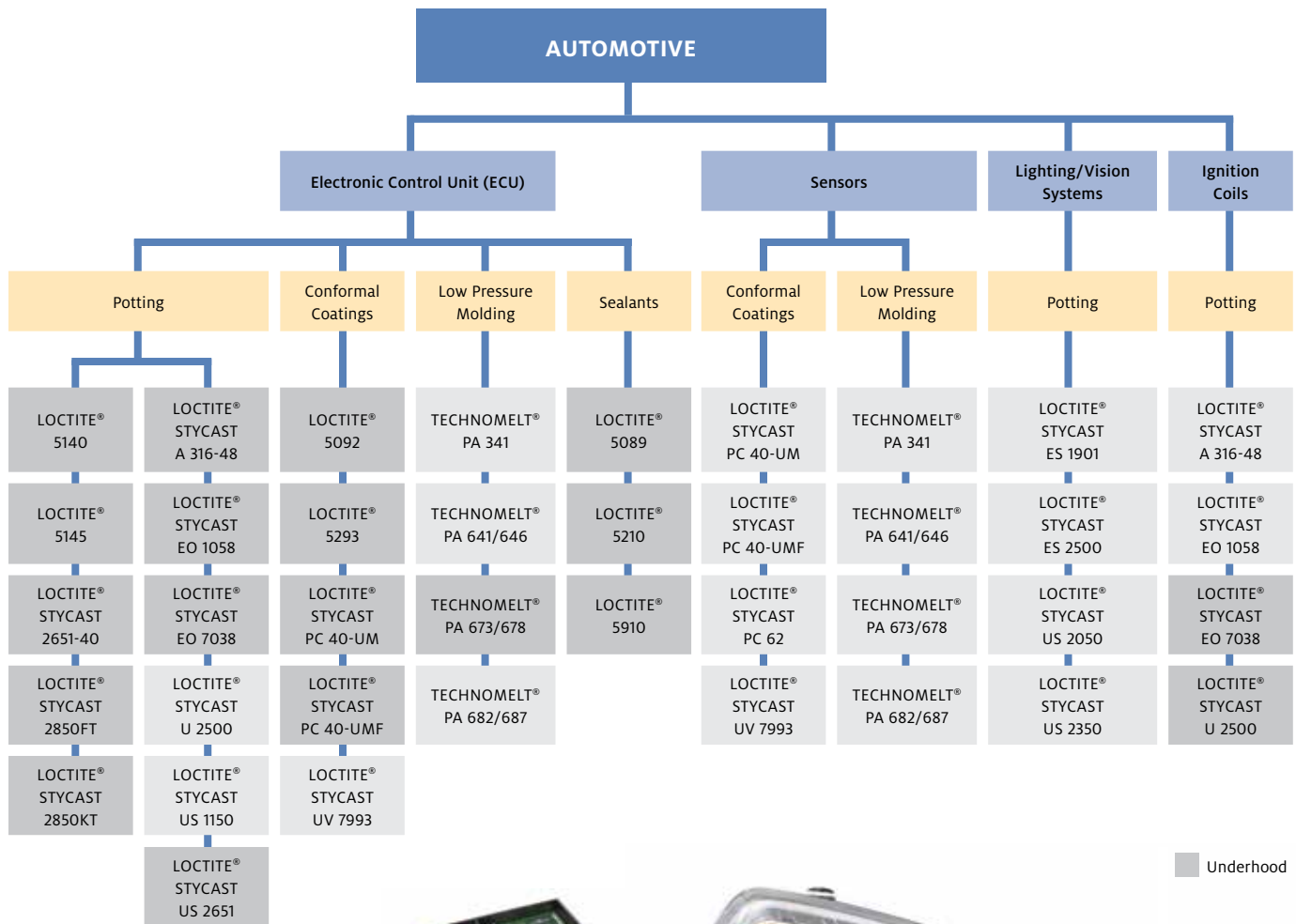
Electronic devices used in automotive applications are constantly subjected to increasingly harsh conditions. Under-the-hood components risk damage from high temperatures. Elsewhere on the vehicle, contaminants from weather, road salts, oils and other automotive fluids can wreak havoc on sensitive and operation-critical electronics. Protecting electronic devices within automotive environments has been Henkel's passion for more than 20 years. Our unique formulations are

found in automotive vision systems, electronic control modules, safety and security systems, sensors and lighting. With potting materials, conformal coatings, sealing and gasketing systems, and low pressure molding solutions, Henkel delivers protection where you need it most – under the hood and on the road.



Printed Circuit Board Protection Market Solutions

Automotive Electronics





Sensors

- Acceleration
- Mass Air Flow
- Occupancy
- Position/Distance
- Speed/Rotation
- Temperature/Pressure

Safety/Security

- Air Bag Systems
- Alarm Systems
- Keyless Entry
- Seat Belt Systems
- Tire Pressure

Vision Systems

- Passenger Detection
- Pre-Crash Warning

Electronic Control Modules

- Air Bag Systems
- Braking Systems
- Energy Systems
- Fuel Pump Drive
- Fuse Boxes
- Heated Washers
- Transmission Systems
- Voltage Regulators

Cabin Devices

- A/V Systems
- Instrument Panels
- Navigation Systems
- Power Modules
- Seat Heaters

Electronic Lighting

- LED Systems



APPLICATIONS	MATERIAL SOLUTIONS
PCB Assembly	<ul style="list-style-type: none"> • Conductive/Non-Conductive Pastes • Film Adhesives • SMT Bonding • Solder • Underfills
PCB Protection	<ul style="list-style-type: none"> • Conformal Coatings • Encapsulants • Low Pressure Molding Adhesives • Potting • Sealants

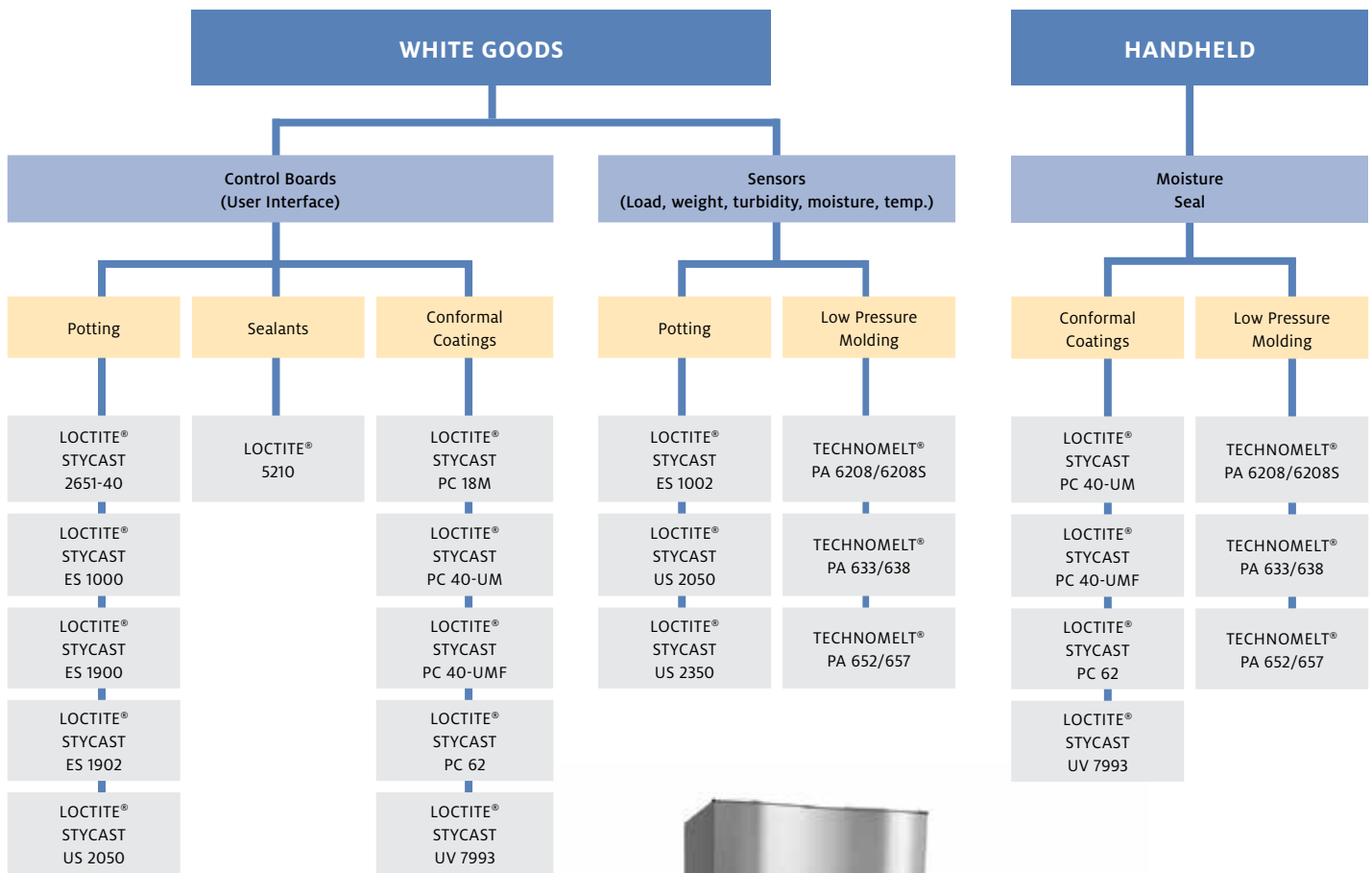
Printed Circuit Board Protection Market Solutions

Consumer Electronics

Everyone who uses consumer electronics has one expectation in common: function without fail. Whether it's a washing machine, dishwasher, smartphone or tablet, immediate response and reliable operation is often taken for granted. Keeping our modern conveniences in good working order, however, takes the protection that Henkel's market-leading conformal coatings and encapsulation materials provide. Without these critical materials, the PCBs, which are arguably the foundation of all consumer electronics, would be nonresistant to corrosion, high temperatures, moisture, vibration and more. Henkel's nimbleness and formulation expertise address the dynamics of this

market with material solutions that deliver real value. Consumers trust that the products they rely on will work on demand, and manufacturers of these products trust Henkel.





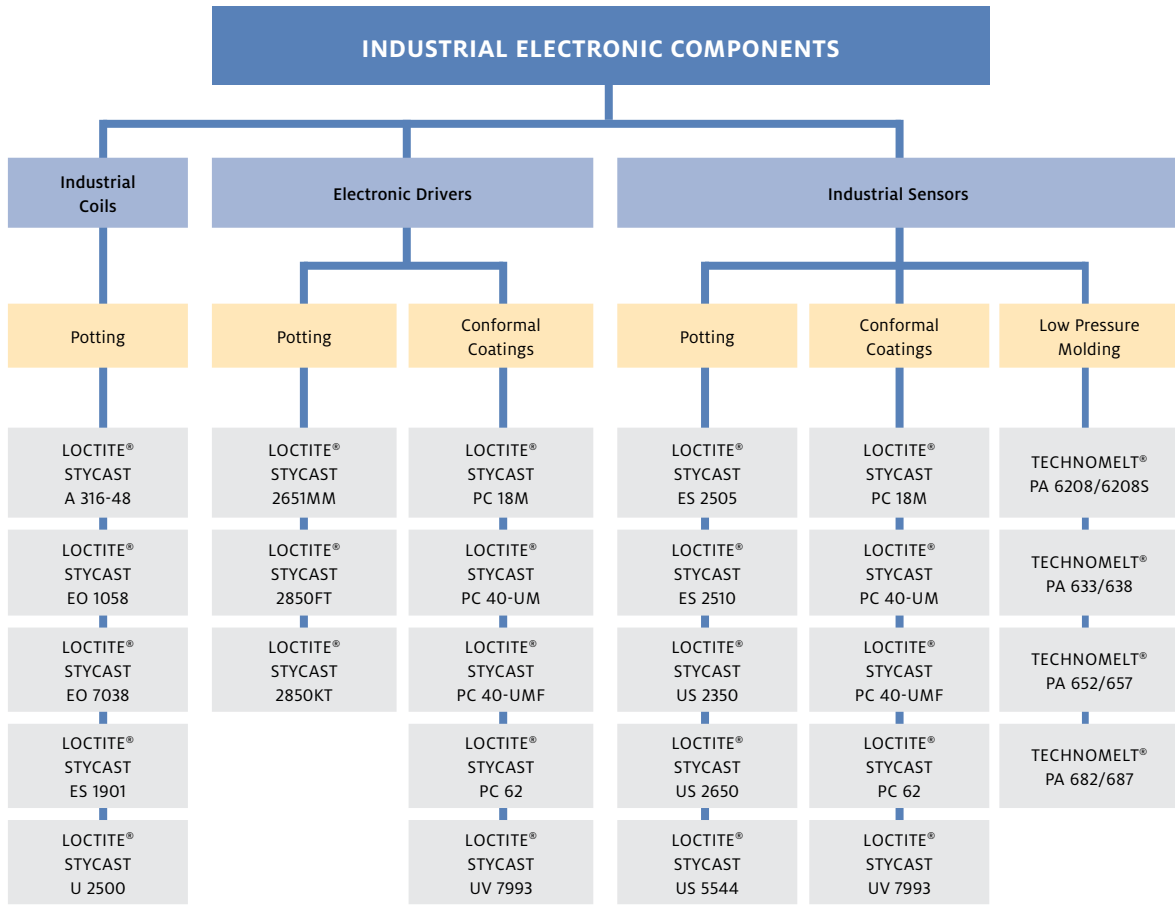
Printed Circuit Board Protection Market Solutions

Industrial Electronic Components

Industrial electronics have to be rugged. They include applications like transformers, water meter sensors, industrial lighting and stadium lighting. Being able to withstand all types of weather conditions, extreme temperature swings and constant operation is par for the course for industrial electronics. Without protective materials, such as Henkel's conformal coatings, potting and low pressure molding compounds, however, the reliability of these important systems would be

compromised. That's why the world's top industrial electronics manufacturing firms partner with Henkel for unfailing performance, exceptional reliability and in-field dependability.





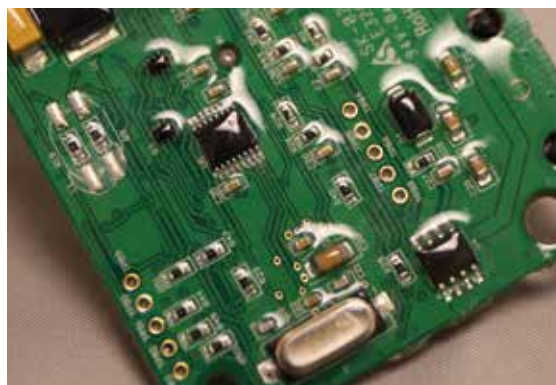
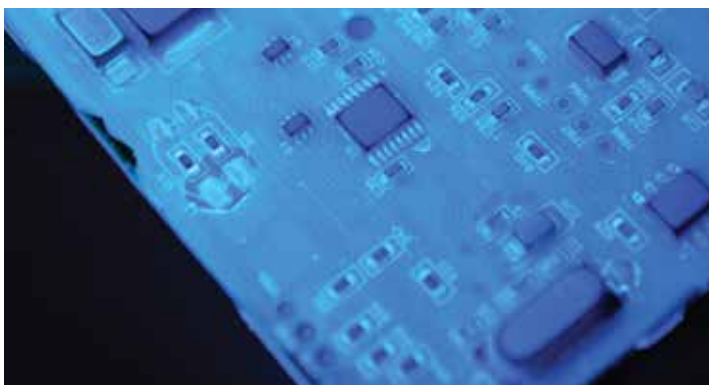
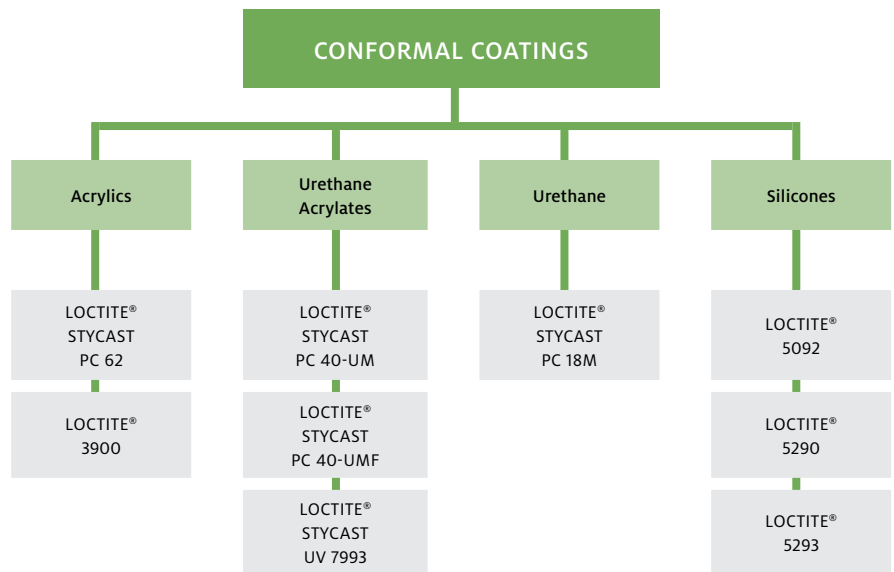


Printed Circuit Board Protection Materials

Conformal Coatings

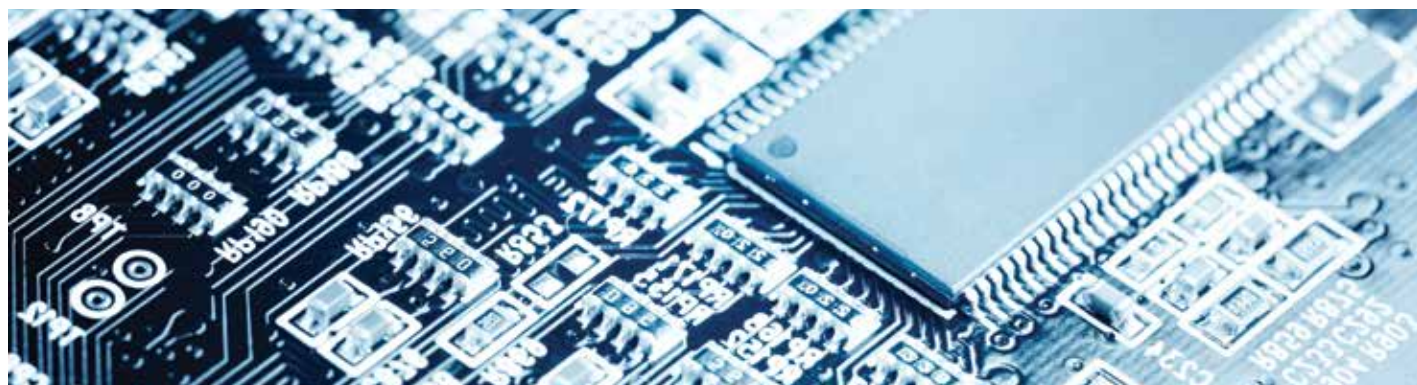
Henkel's advanced LOCTITE® brand of conformal coating materials protect PCBs and advanced substrates from thermal shock, moisture, corrosive liquids and other adverse environmental conditions. Shielding electronic function from external influences ensures long product life cycles for harsh marine, automotive, medical and consumer electronics applications.

With exceptionally fast-cure capability and 100 percent solvent-free formulations, Henkel's conformal coatings provide fast processing and are environmentally responsible.





PRODUCT	DESCRIPTION	CURE SCHEDULES	VISCOSITY mPa·S (cP)	OPERATING TEMPERATURE RANGE
ACRYLICS				
LOCTITE® STYCAST PC 62	Conformal coating that provides environmental and mechanical protection. Toluene-free alternative with superior toughness and abrasion resistance.	45 min. @ 75°C	50	-40°C to 125°C
LOCTITE® 3900	Aerosol, fast-cure, solvent-based acrylic coating. Designed for small product runs.	Air dry - 5 min.	N/A (Aerosol)	-40°C to 125°C
URETHANE ACRYLATES				
LOCTITE® STYCAST PC 40-UM	One-component, solvent-free conformal coating that gels rapidly and cures with UV/moisture.	30 sec. UV + 3 days @ RT	500	-40°C to 135°C
LOCTITE® STYCAST PC 40-UMF	Conformal coating specifically formulated to rapidly gel and immobilize when exposed to UV light and then fully cure when exposed to atmospheric moisture, ensuring optimum performance even in shadowed areas.	10 sec. UV + 3 days @ RT	250	-40°C to 135°C
LOCTITE® STYCAST UV 7993	Conformal coating designed to provide rugged protection from moisture and harsh chemicals. It is compatible with industry-standard solder masks, no-clean fluxes, metalization, components and substrate materials.	10 sec. UV + 50 hours @ > 70% RH	120	-40°C to 105°C
URETHANE				
LOCTITE® STYCAST PC 18M	Flexible, one-component, solvent-based urethane coating that may be cured at room temperature.	2 hrs. @ 60°C w/ 30-50% RH	350	-40°C to 110°C
SILICONES				
LOCTITE® 5092	Noncorrosive, UV/moisture-cure silicone for shallow potting, coating and sealing of electronic assemblies. High adhesion to difficult-to-bond substrates.	60 sec. UV + 3 days @ RT	5,800	-40°C to 200°C
LOCTITE® 5290	UV/moisture cure silicone conformal coating. Designed for severe temperature environments. High-reliability automotive applications. Solvent-free.	20 sec. UV + 3 days @ RT	300	-40°C to 200°C
LOCTITE® 5293	Repairable, solvent-free, medium-viscosity, UV/ moisture-cure silicone, designed for severe temperature environments. High-reliability automotive applications.	20 sec. UV + 3 days @ RT	600	-40°C to 200°C



Printed Circuit Board Protection Materials

Low Pressure Molding

TECHNOMELT®, Henkel's unique polyamide hot melt material, provides a low pressure molding solution with superior sealing adhesion and excellent temperature and solvent resistance.

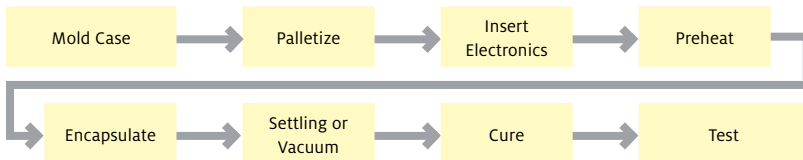
TECHNOMELT® quickly encapsulates exposed circuitry to form the outer shell of the device and delivers a self-contained integrated assembly. Low application pressure between 20 and 500 psi within the mold cavity safeguards sensitive circuitry. When in a liquid state, TECHNOMELT® flows in and around the tightest dimensions without the high levels of pressure used with traditional injection molding or potting techniques, and significantly reduces stress even for the most highly miniaturized components.

TECHNOMELT® cycle time is very short, allowing for a high throughput process, and its functional design enables manufacturers to remove process steps. This novel material from Henkel has found application in a variety of products within the automotive, medical, industrial and consumer markets.

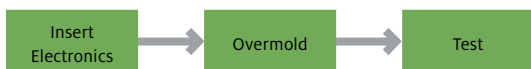


Process

Traditional potting process flow



Low pressure process flow



Key Benefits

Design

- Additive design allows for alternative solutions (simplified process vs. traditional technologies)
- “Sky Lining” allows the use of less material, precise encapsulation and less weight
- Functional design removes process steps
- Improved look and image

Process

- Reduces total cost of ownership (TCOO)
- Increased throughput
- Low capital equipment costs and reduced footprint
- Low-viscosity materials allow for low injection pressures

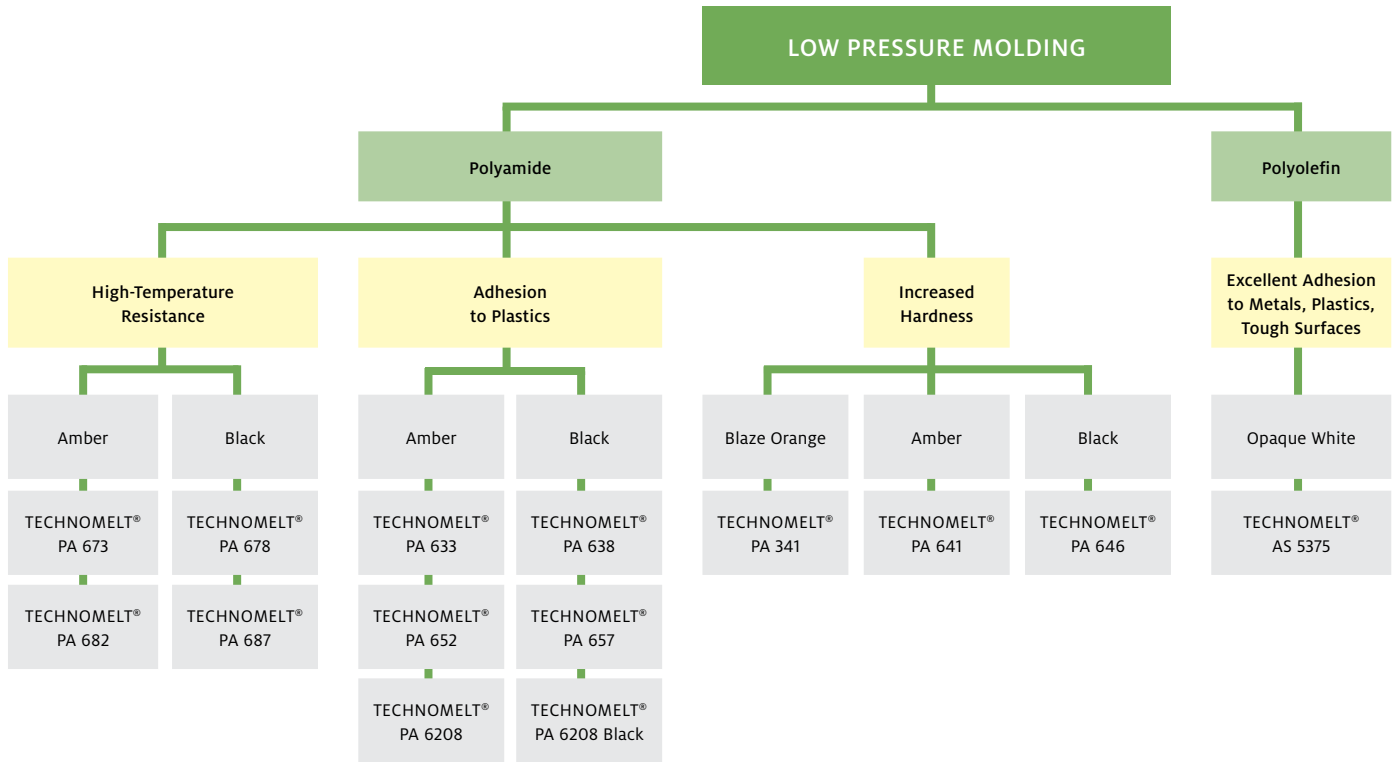
Products

- Adhesion to multiple surfaces
- Complete watertight encapsulation
- Safe, one component, UL 94-V0 approved
- High-temperature resistance
- Compliant materials suitable for sensitive electronic components
- Less handling and shorter process
- No cure process required

Sustainability

- Zero waste
- All excess material and scrap are recyclable
- Natural ingredients

Through the combination of design, process, product and sustainability, Low Pressure Molding with TECHNOMELT® delivers customers an advanced and environmentally sustainable solution to Circuit Board Protection.



PRODUCT	DESCRIPTION	COLOR	PERFORMANCE TEMPERATURE	SHORE A HARDNESS	SOFTENING POINT
POLYAMIDE: HIGH TEMPERATURE RESISTANCE					
TECHNOMELT® PA 673	Moldable polyamide with good adhesion for higher-temperature applications, such as in an automotive underhood.	Amber	-40°C to 140°C	90	187°C ± 5°C
TECHNOMELT® PA 678		Black			
TECHNOMELT® PA 682	Moldable polyamide for the most demanding high-humidity applications, such as on the inside of an automobile tire. Formulated for very low water vapor transmission.	Amber	-40°C to 140°C	88	188°C ± 5°C
TECHNOMELT® PA 687		Black			
POLYAMIDE: ADHESION TO PLASTICS					
TECHNOMELT® PA 633	Moldable polyamide with service temperature up to 130°C, such as in an automotive firewall.	Amber	-40°C to 130°C	90	175°C ± 5°C
TECHNOMELT® PA 638		Black			
TECHNOMELT® PA 652	Moldable polyamide where excellent adhesion and cold-temperature flexibility are important, such as in an automotive exterior. Also used extensively in white goods.	Amber	-40°C to 100°C	77	157°C ± 5°C
TECHNOMELT® PA 657		Black			
TECHNOMELT® PA 6208	Moldable polyamide with excellent adhesion to tough substrates. Great flexibility offers incredible strain relief on cables and wires. Ideal for encapsulation of heat-producing components in appliances and consumer electronics, UL RTI 95°C.	Amber	-40°C to 110°C	78	155°C ± 5°C
TECHNOMELT® PA 6208 BLACK		Black			
POLYAMIDE: INCREASED HARDNESS					
TECHNOMELT® PA 341	High-performance, thermoplastic polyamide designed to offer blaze orange color for easy identification of components. Typically used to encapsulate high-voltage modules.	Blaze Orange	-25°C to 125°C	92	173°C ± 5°C
TECHNOMELT® PA 641	Moldable polyamide where strength and hardness are needed, such as in memory sticks and computer connectors.	Amber	-40°C to 130°C	92	175°C ± 5°C
TECHNOMELT® PA 646		Black			
POLYOLEFIN: EXCELLENT ADHESION TO METALS, PLASTICS, TOUGH SURFACES					
TECHNOMELT® AS 5375	Moldable polyolefin for resistance against moisture and solvents. Excellent adhesion to the most difficult substrates. Compatible with a secondary overmold with a harder polyamide.	Opaque White	-30°C to 100°C	55	139°C ± 5°C

Printed Circuit Board Protection Materials

Sealants

Effective sealing of electronic components and modules protects complex, fine-pitch components from excessive thermal shock and high-temperature exposure. Henkel's silicone-based LOCTITE® sealant and encapsulant materials offer precise and reliable safeguarding of sensitive electronics against the damaging effects of moisture, while also improving thermal cycling performance.

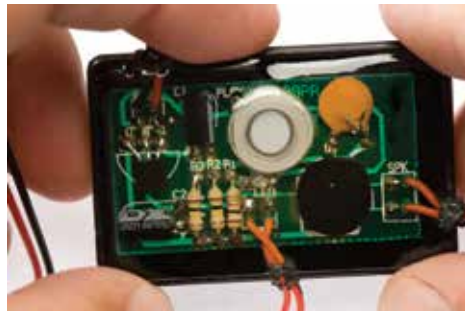
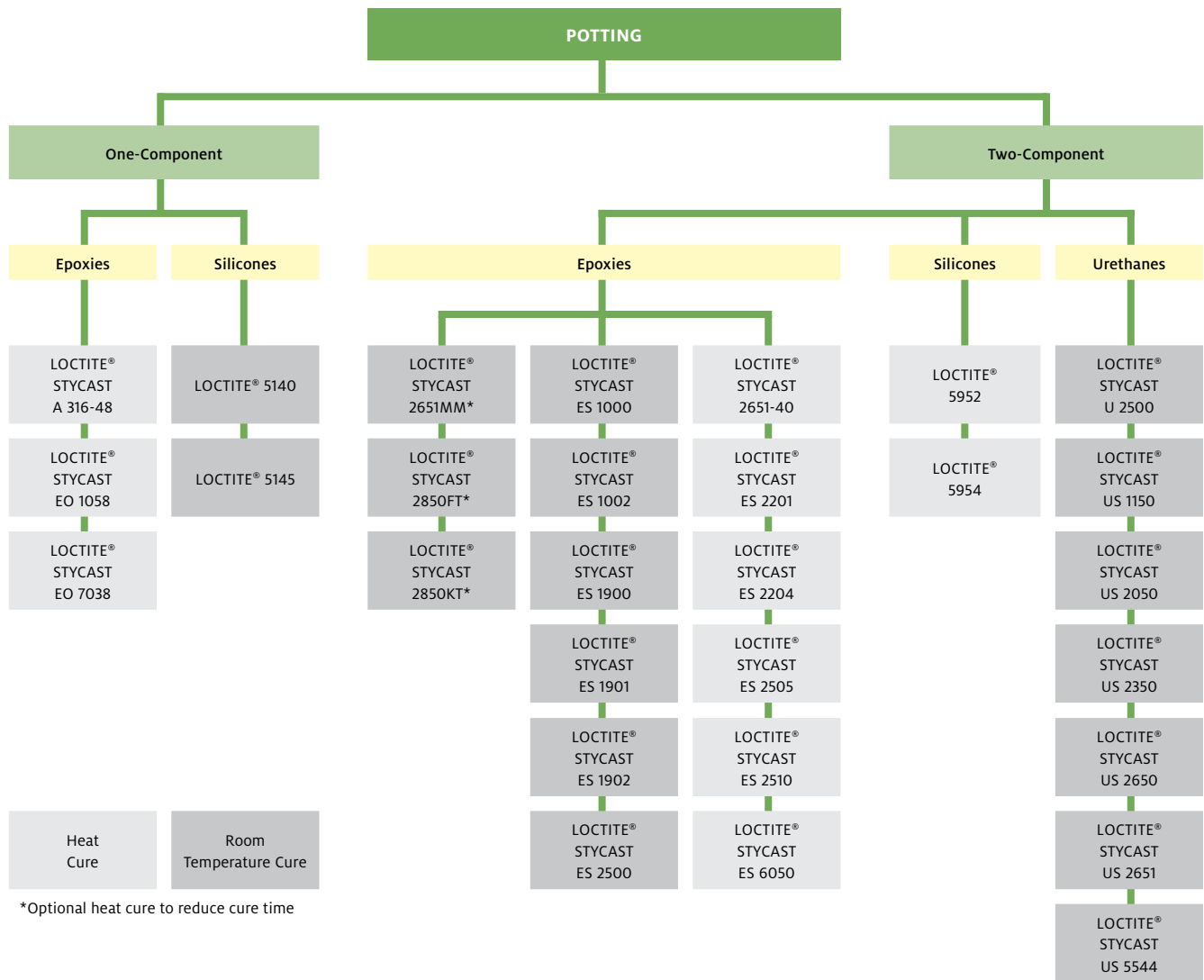
Henkel's sealant materials are UV curable to enable fast processing; environmentally responsible with reduced solvent content; conveniently packaged for dispense operations; and offer exceptional ease of use. These advanced formulations are suitable for a wide variety of applications and manufacturing requirements.



PRODUCT	DESCRIPTION	CURE SCHEDULES	CHEMISTRY	VISCOSITY (cP)	SHORE A HARDNESS
LOCTITE® 5089	Used for gasketing and sealing applications. Upon exposure to sufficient UV light and/or atmospheric moisture, this product cures to form a durable, flexible rubber sealant. Typical applications include gasketing/sealing of enclosures that require a rapid-curing, post-applied sealant that facilitates immediate on-part inspection.	60 sec. UV + 3 days RT	Alkoxy silicone	100,000	>25
LOCTITE® 5210	One-component, ultra-fast-curing, noncorrosive RTV silicone designed for potting, wire tacking, selective sealing, vibration dampening and repair/rework applications on PCBs. Suited for high-volume manufacturing and is particularly effective for automotive electronics applications or other harsh environments. Fast surface cure allows material to be handled quickly after dispensing.	24 hrs. @ 25°C	Alkoxy silicone	Extrusion rate-400 gm/min.	48
LOCTITE® 5910	One-component silicone sealant. Typical applications include stamped sheet metal covers (timing covers and oil sumps) where good oil resistance and the ability to withstand high-joint movement is required.	7 days @ 25°C	Oxime silicone	Extrusion rate-600 gm/min.	30
LOCTITE® 5964	Heat-cured, cure-in-place gasket. Soft with high elongation. Compressible. Can be cured with heat or VFM.	10 min. @ 150°C or 4 min. using VFM	Heat cure silicone	Extrusion rate-150 gm/min.	28

Printed Circuit Board Protection Materials

Potting



Printed Circuit Board Protection Materials

Potting

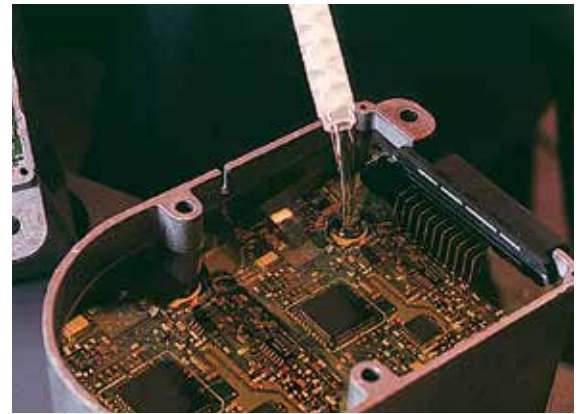
Potting and encapsulation systems from Henkel offer superb protection of printed circuit boards and electrical devices. Used in today's most challenging environments, such as automotive and defense/aerospace, where thermal conductivity and

operating-temperature boundaries are pushed to the limit, potting materials deliver enhanced mechanical strength, provide electrical insulation and improve thermal reliability.

PRODUCT	DESCRIPTION	MIX RATIO BY WEIGHT	COLOR	
ONE-COMPONENT EPOXIES				
LOCTITE® STYCAST A 316-48	One-component epoxy system. Pourable. Designed for harsh automotive applications. Fast cure. Room-temperature stable. Excellent thermal stability and chemical resistance.	NA	Black	
LOCTITE® STYCAST EO 1058	One-component epoxy potting compound formulated to protect automotive sensors used in harsh environments. Provides excellent environmental and thermal protection.	NA	Black	
LOCTITE® STYCAST EO 7038	One-component epoxy potting compound formulated to protect automotive sensors used in harsh environments.	NA	Black	
ONE-COMPONENT SILICONES				
LOCTITE® 5140	Noncorrosive, self-leveling RTV silicone. Designed for shallow potting, sealing and coating of electronics.	NA	Clear	
LOCTITE® 5145	High-strength, noncorrosive form-in-place RTV silicone adhesive for bonding and sealing electrical devices.	NA	Clear	
TWO-COMPONENT EPOXIES				
LOCTITE® STYCAST 2651MM	Filled, general-purpose, epoxy encapsulant that requires low viscosity and low abrasion. It is especially useful for machine dispensing and for parts that require post-molding machining.	100:7.0 (CAT 9)	Black	
LOCTITE® STYCAST 2850FT	Two-component, thermally conductive epoxy encapsulant that can be used with a variety of catalysts. Used in the encapsulation of components that need heat dissipation and thermal shock properties.	100:3.5 (CAT 9)	Black	
LOCTITE® STYCAST 2850KT	Two-component, thermally conductive epoxy encapsulant designed for replacement for heat sinks in non-integrated electrical components and assemblies.	100:2.0 (CAT 9)	Black	
LOCTITE® STYCAST ES 1000	Two-component casting system with a long pot life. This low-cost, flexible system is filled with a non-abrasive filler for machine metering/dispensing. Good thermal shock resistance and low exotherm, making it suitable for encapsulation of various components and modules.	100:90	Black	
LOCTITE® STYCAST ES 1002	Two-component casting system with excellent handling properties. This low-cost, flexible system is filled with a non-abrasive filler for machine metering/dispensing or regular hand mixer applications.	100:100	Black	
LOCTITE® STYCAST ES 1900	Transparent, medium-viscosity, epoxy resin formulation recommended for small potting and laminating applications where clarity and excellent structural, mechanical and electrical properties are required.	100:46	Clear	
LOCTITE® STYCAST ES 1901	Fast-setting, toughened, medium-viscosity, industrial-grade epoxy adhesive. Ideal for bonding plastic, metal, glass, wood, ceramic, rubber and masonry materials where flexibility is needed. Designed for a variety of applications, such as flex circuits, cable boots and staking fillet bonds.	100:105	Clear	



Henkel's potting formulas provide excellent adhesion strength to all surface types and are electrically insulating and thermally stable with a broad operating temperature range. Applications such as insulation of electronic components, protection of electronic control modules in automotive and defense/aerospace devices, and environmental safeguarding of consumer electronics like LED sign boards are all made more reliable with Henkel's potting and encapsulation materials.



	RECOMMENDED CURE SCHEDULE	ALTERNATE CURE CYCLE	VISCOSITY cP AT 25°C	POT LIFE AT 25°C	HARDNESS	THERMAL CONDUCTIVITY W/M°C	FLAMMABILITY RATING	TEMPERATURE RANGE	SHELF LIFE
	3 min. @ 140°C	30 min. @ 100°C	50,000	3 months	86D	0.4	None	-40°C to 180°C	3 months @ 25°C
	2 hrs. @ 140°C	3 hrs. @ 125°C	50,000	10 days	90D	0.5	None	-40°C to 180°C	7 months @ 5°C
	2 hrs. @ 140°C	2 hrs. @ 90°C plus 2 hrs. @ 130°C	40,000	3 days	92D	ND	None	-40°C to 180°C	4 months @ 5°C or 12 months @ -20°C
	72 hrs. @ 25°C	NA	35,000	skin over in 3 hrs.	30A	ND	None	-55°C to 205°C	12 months @ 25°C
	72 hrs. @ 25°C	NA	extrusion rate 200 g/min.	skin over in 3 hrs.	33A	0.2	None	-55°C to 205°C	12 months @ 25°C
	24 hrs. @ 25°C	2 hrs. @ 65°C	14,000	45 min.	88D	0.6	None	-40°C to 205°C	1 year
	24 hrs. @ 25°C	2 hrs. @ 65°C	58,000	45 min.	96D	1.25	None	-40°C to 130°C	1 year
	24 hrs. @ 25°C	2 hrs. @ 65°C	174,000	10 min.	94D	2.68	None	-40°C to 130°C	1 year
	36 hrs. @ 25°C	2 hrs. @ 60°C	25,000	180 min.	75D	0.42	94HB	-25°C to 105°C	1 year
	36 hrs. @ 25°C	2 hrs. @ 60°C	19,500	60 min.	88D	0.64	94V-0	-25°C to 105°C	1 year
	24 hrs. @ 25°C	2 hrs. @ 65°C	6,000	10 min.	90D	0.2	None	-60°C to 125°C	1 year
	24 hrs. @ 25°C	1 hr. @ 65°C	2,400	3 min.	55D	0.2	None	-40°C to 105°C	1 year

Printed Circuit Board Protection Materials

Potting

PRODUCT	DESCRIPTION	MIX RATIO BY WEIGHT	COLOR	
TWO-COMPONENT EPOXIES <i>continued</i>				
LOCTITE® STYCAST ES 1902	Two-part, transparent, low-viscosity UV epoxy. Designed for potting and laminating applications where low color and excellent electrical and mechanical properties are desired. This material exhibits a fast UV gellation followed by room temperature cure. The ES 1902 has low shrinkage and bonds to most metals and many rigid plastics.	100:41.7	Clear	
LOCTITE® STYCAST ES 2500	Resilient, low-cost, fast-gelling potting compound. Designed for easy 2-to-1 meter mix-dispense machinery and low abrasion. This material is ideal for potting and encapsulating high-volume parts.	100:29.5	Black	
LOCTITE® STYCAST 2651-40	Low-viscosity, general-purpose epoxy encapsulant. Excellent adhesion to metals, plastics and ceramics. Compatible with CAT 9, CAT 11 and CAT 23LV.	100:9 (w/CAT 9)	Black	
LOCTITE® STYCAST ES 2201	Unfilled, low-viscosity epoxy casting system with exceptional resistance to impact and thermal shock. Adheres well to lead and wire materials like PVC, vinyl and neoprene.	100:30	Amber	
LOCTITE® STYCAST ES 2204	Filled, low-viscosity epoxy casting system. Recommended for potting where high-impact strength is required. Adheres well to lead and wire materials like PVC, vinyl and neoprene.	100:15	Black	
LOCTITE® STYCAST ES 2505	Low-viscosity, filled, dielectric-grade epoxy encapsulant designed for general-purpose applications. It is suitable for potting and encapsulating electrical devices that require flame retardancy. ES 2505 is RoHS-compliant version of 2651-40FR. Compatible with CAT 9, CAT 11 and CAT 23LV.	100:9.5 (w/CAT 11)	Black	
LOCTITE® STYCAST ES 2510	Low-viscosity, dielectric-grade epoxy encapsulant designed for general-purpose applications. It is suitable for potting and encapsulating electrical devices that require flame retardancy. Excellent dielectric properties. ES 2510 is RoHS-compliant version of LA9823-76. Compatible with CAT 9 and CAT 11.	100:57	Beige	
LOCTITE® STYCAST ES 6050	Filled, low volatile potting and sealing epoxy.	100:19.3	Pink	
TWO-COMPONENT SILICONES				
LOCTITE® 5952	Two-part, addition-cure silicone encapsulant. Good thermal conductivity. Noncorrosive. Excellent electrical properties.	1:1	Red	
LOCTITE® 5954	Two-part, highly filled, addition-cure, thermally conductive silicone. High thermal conductivity. Noncorrosive.	1:1	Red	
TWO-COMPONENT URETHANES				
LOCTITE® STYCAST U 2500	Encapsulant designed for transformers, PCBs and other insulation applications. Allows complete impregnation of either small, slightly wound coils or large castings.	100:07	Amber	
LOCTITE® STYCAST US 1150	Extended polybutadiene/MDI base, mineral-filled, medium-hardness, ambient-cure urethane encapsulant/sealant. This material can be used for potting electronics or devices for protection against environmental hazards.	21:100	Black	
LOCTITE® STYCAST US 2050	Quick-setting, optically clear polyurethane compound that exhibits excellent ultraviolet resistance. The excellent electrical properties also suggest its use for electrical and electronic component encapsulation.	100:55	Clear	
LOCTITE® STYCAST US 2350	Flexible, flame-retardant, mineral-filled polyurethane compound. This low-viscosity potting compound has a long pot life and adheres to many substrates.	21.2:100	Black	
LOCTITE® STYCAST US 2650	Inexpensive, low-viscosity, flexible, flame-retardant, castor oil/MDI-based urethane potting/encapsulating compound. This material was designed for potting indoor and outdoor telephone connector blocks. It is suitable for potting and encapsulating other electronic or electrical devices or assemblies.	21.1:100	Tan	
LOCTITE® STYCAST US 2651	Unfilled, low-viscosity, re-enterable potting and encapsulation compound. It can be used to encapsulate electronics for automotive applications, including under the hood.	52.3:47.7	Clear Amber	
LOCTITE® STYCAST US 5544	Fast-gelling, flexible, flame-retardant urethane encapsulant. Low-viscosity material that flows well and adheres to a variety of substrates.	15:85	Opaque White	

	RECOMMENDED CURE SCHEDULE	ALTERNATE CURE CYCLE	VISCOSITY cP AT 25°C	POT LIFE AT 25°C	HARDNESS	THERMAL CONDUCTIVITY W/M°C	FLAMMABILITY RATING	TEMPERATURE RANGE	SHELF LIFE
	UV- 20 sec. at 200mW/cm ² plus 24 hrs. @ 25°C	2 hrs. @ 60°C	290	60 min.	80D	0.2	None	-40°C to 110°C	1 year
	16 hrs. @ 25°C	2 hrs. @ 65°C	1,500	10 min.	70D	0.288	94HB	-40°C to 105°C	1 year
	2 hrs. @ 65°C	24 hrs. @ 25°C	5,000	45 min.	88D	0.55	None	-40C to 130C	1 year
	24 hrs. @ 25°C	2 hrs. @ 60°C	600	35 min.	80D	0.21	None	-40°C to 125°C	1 year
	24 hrs. @ 25°C	2 hrs. @ 60°C	2,000	80 min.	85D	0.46	None	-40°C to 125°C	1 year
	60 min. at 120°C (w/CAT 11)	4 hrs. @ 100°C (w/CAT 11)	5,000	>4 hrs.	72D	0.82	94V-0	-55°C to 155°C	1 year
	2 hrs. @ 60°C	16 hrs. @ 40°C	5,500	2.5 hrs.	70D	0.5	94V-0	-40°C to 125°C	1 year
	24 hrs. @ 25°C	2 hrs. @ 60°C	8,000	30 min.	80D	ND	None	-40°C to 100°C	1 year
	48 hrs. @ 25°C	2 hrs. @ 65°C	40,000	100 min.	75A	0.85	None	-65°C to 260°C	6 months @ 25°C
	48 hrs. @ 25°C	4 hrs. @ 65°C	35,000	90 min.	85A	2.45	None	-65°C to 260°C	6 months @ 25°C
	24 hrs. @ 25°C	4 hrs. @ 60°C	6,600	2 hrs.	72A	0.49	None	-40°C to 125°C	6 months
	24 to 48 hrs. @ 25°C	2 to 4 hrs. @ 60°C	3,500	40 to 60 min.	60A	0.486	94V-0	-65°C to 125°C	1 year
	48 hrs. @ 25°C	2 hrs. @ 60°C	1,200	4 min.	90A	0.18	None	-40°C to 125°C	1 year
	24 hrs. @ 25°C	2 hrs. @ 60°C	2,400	45 min.	85A	0.51	94V-0	-65°C to 125°C	1 year
	16 hrs. @ 25°C	1 hr. @ 60°C	3,500	19.5 min.	83A	0.47	94V-0	-65°C to 125°C	1 year
	16 hrs. @ 25°C	1 hr. @ 65°C	1,000	10 min.	15A	0.18	None	-65°C to 125°C	1 year
	4 hrs. @ 25°C	30 min. @ 85°C	2,000	3 min.	85A	0.35	94V-0	-65°C to 125°C	1 year

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